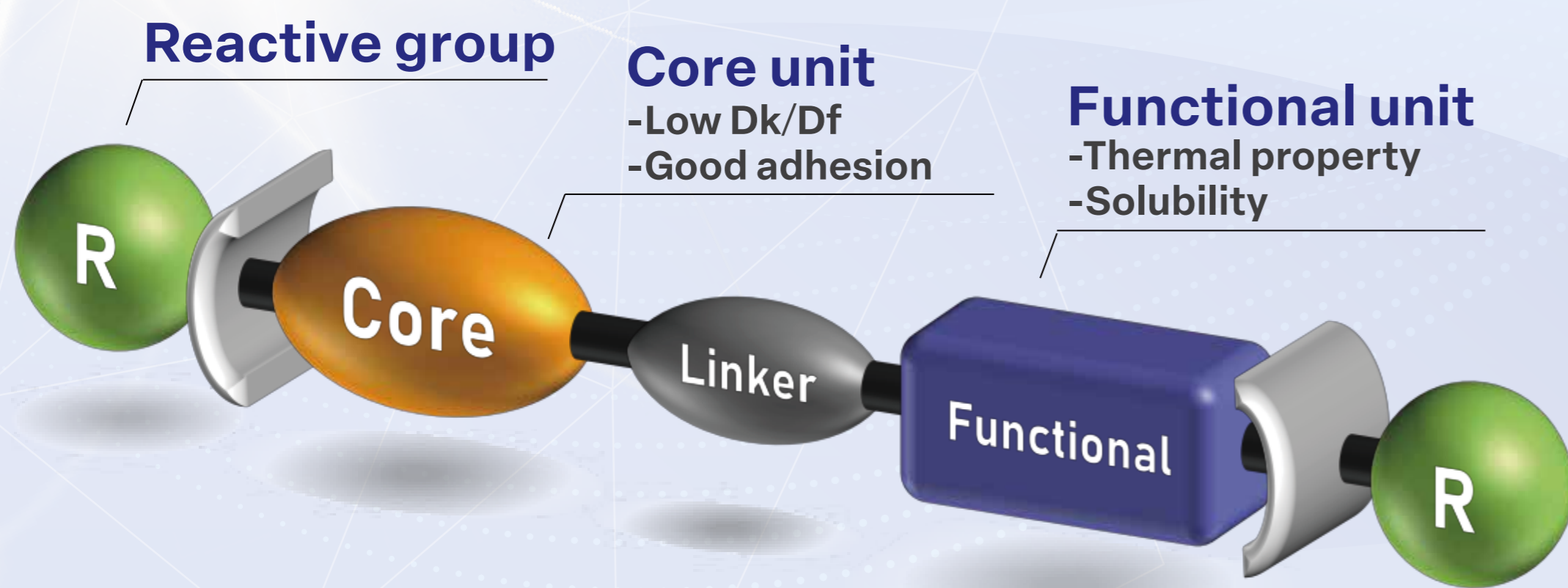


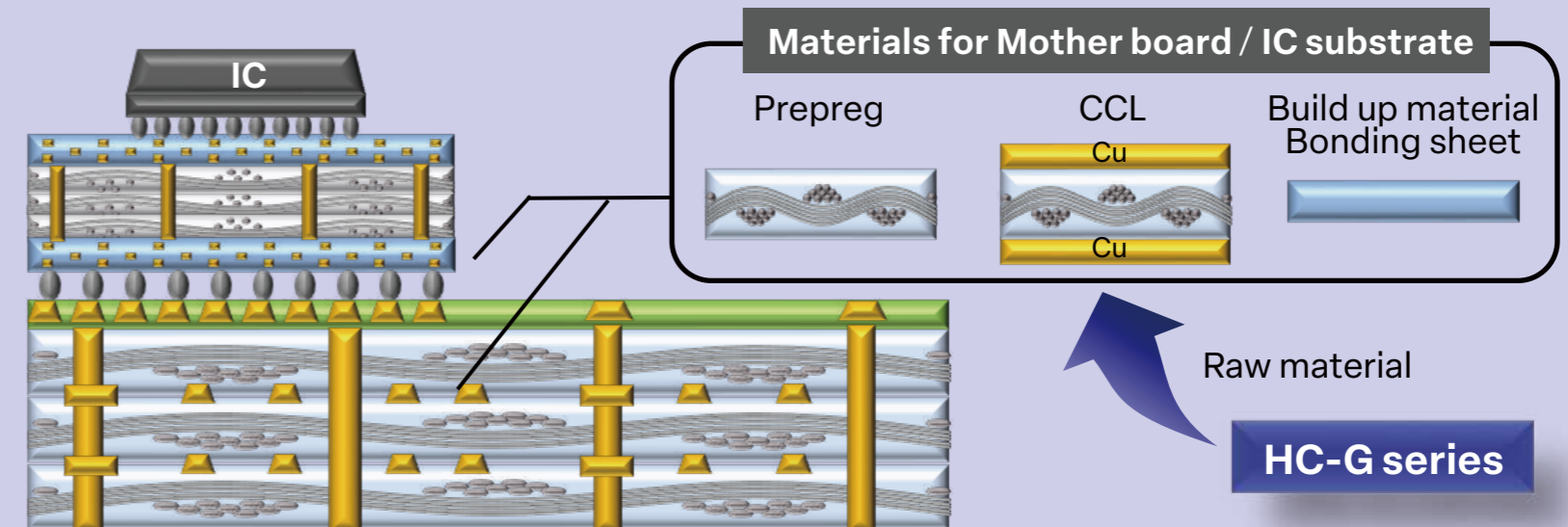
JSR ELPAC™ HC-G series

Design Concept





Application

- Expected to be useful as a raw material for circuit board
 - ✓ High speed communication for Data Center / AI
 - ✓ High Frequency for Antenna, Radar, Sensor and etc.
 - ✓ Low Dk / Df IC substrate



Properties of cured film

	HC-G Type 1	HC-G Type 2
Feature	Low Df Good adhesion	Low Df High Tg
	Structure A	Structure B
	Radical-curable	
Dk (10GHz)	2.6	2.6
Df (10GHz)	0.0011	0.0009
Tg (°C, DMA)	172	233
T _d ⁵ (°C)	390	399
Peel strength(N/mm)	0.8	0.6
Appearance		

Composition: HC-G polymer / Organic peroxide. Cured at 200°C

Durability of cured film

Change of Dk & Df [Value at after test - Value at initial]

Composition: Resin/Organic peroxide/Curing condition: 200°C Test condition: 150°C×500h under air

